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# CSTIC 2023 Summary

June 26-July 27, 2023

Shanghai, China

[www.semiconchina.org/cstic](http://www.semiconchina.org/cstic)   [v.semi.org.cn/cstic](http://v.semi.org.cn/cstic)





# Plenary Session and Award Winners





# Plenary Speakers

2023 CSTIConference, June 26-27, 2023, Shanghai  
Albert Fert, Université Paris-Saclay, Umr CNRS-Thales

Switching greener with spintronics and **prospects far beyond**

Thanks to my coworkers at UMR CNRS/Thales at Université Paris-Saclay  
and acknowledgements of collaborations



SPINTEC, Grenoble, Un. de Lorraine, Nancy,  
Beihang University, Beijing, China  
Colorado St. Un., Fort Collins, CO, USA  
Western Dig. Corp., San Jos , CA, USA  
Intel Corp., Hillsboro, OR, USA



Spintronics for Greener Digital Technologies and  
Prospects Far Beyond

**Prof. Albert Fert**

**Research Director, Unit  Mixte de Physique,  
Nobel Laureate in 2007**

Innovations Boost Integrated Circuit

**Prof. Ming Liu**

**Academician of CAS, Fudan University**

Advanced Packaging Technology Challenges: an  
Equipment Supplier's Perspective

**Dr. Yang Pan**

**Corporate Vice President, Lam Research**

Endless Technological Innovation in IC Equipment

**Mr. Jinrong Zhao**

**Chairman of the Executive Committee, Beijing  
NAURA Technology Group**

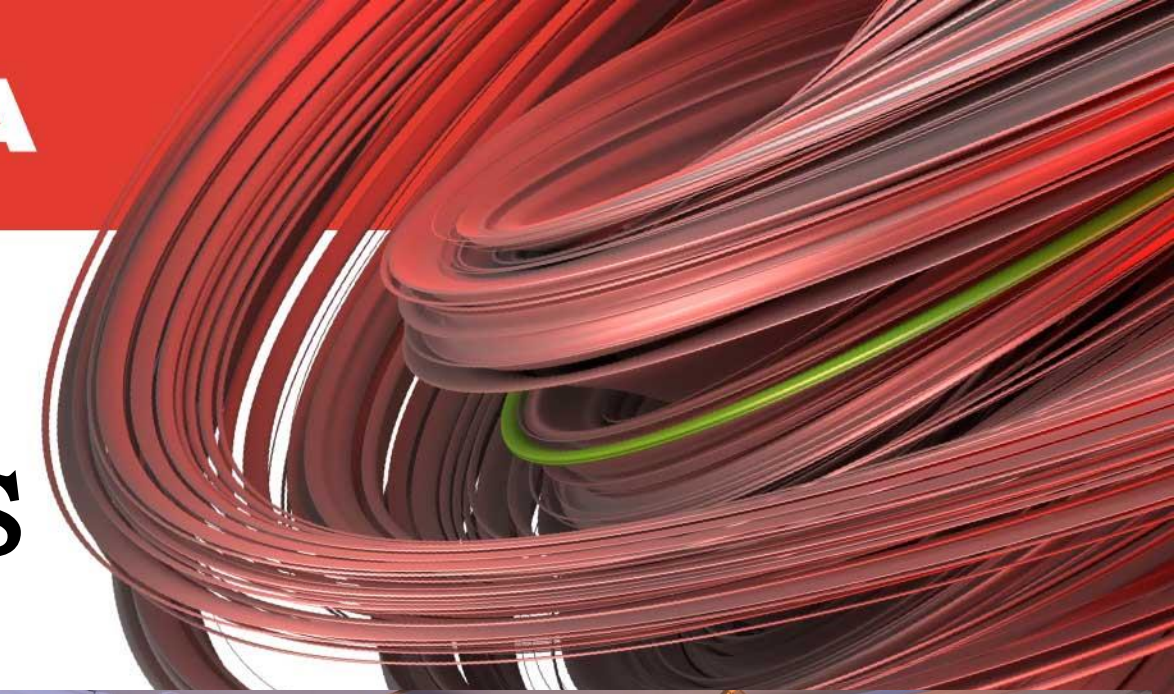
From Legacy to Leading Edge: Broadband Wafer  
Optical Inspection for Process Control

**Dr. Yalin Xiong**

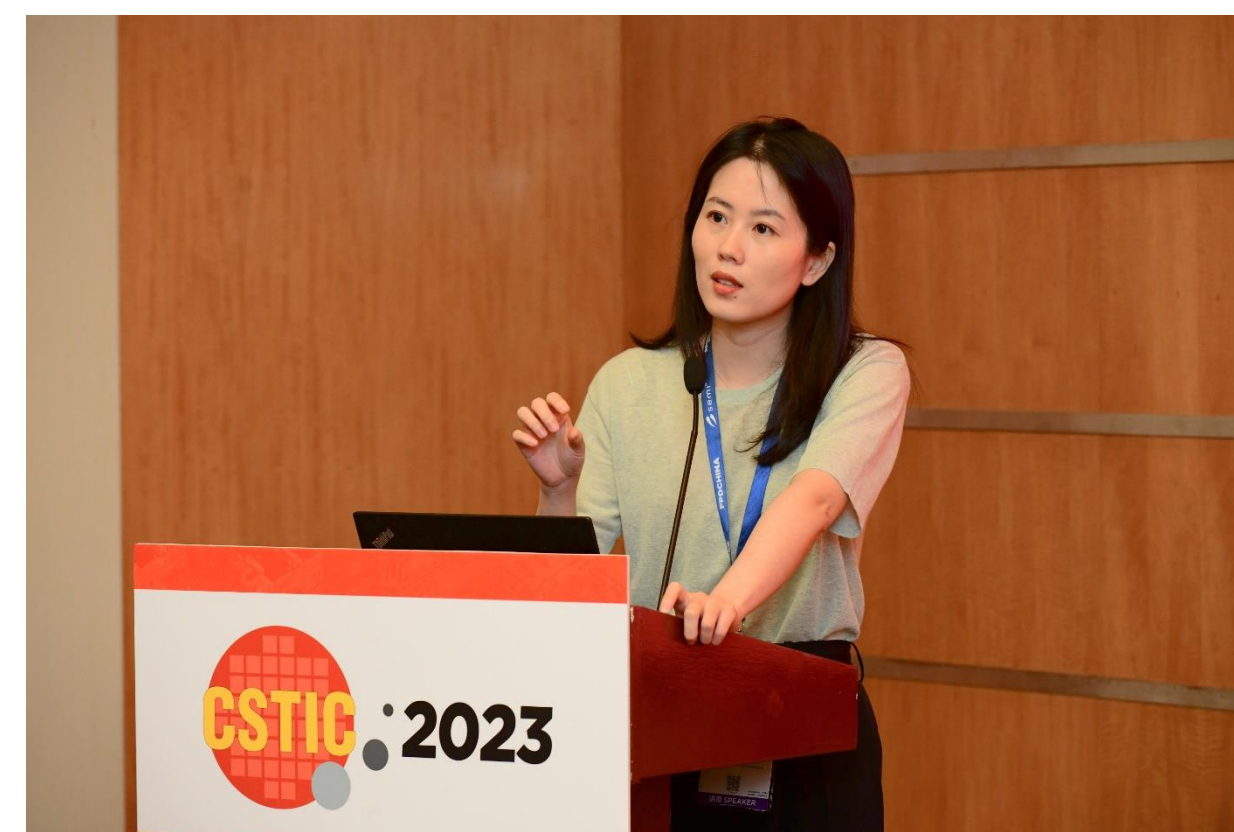
**Senior Vice President and General Manager, KLA  
Corporation**







# >170 Oral Presentations and >180 Posters





# 9 Symposia with 100 Invited Speakers

**Symp I: Device Engineering and Memory Technology**

**Symp. II: Lithography and Patterning**

**Symp. III: Dry & Wet Etch and Cleaning**

**Symp. IV: Thin Film, Plating and Process Integration**

**Symp. V: CMP and Post CMP Cleaning**

**Symp. VI: Metrology, Reliability and Testing**

**Symp. VII: Packaging and Assembly**

**Symp. VIII: MEMS, Sensors and Emerging Semiconductor Technologies**

**Symp. IX: Design and Automation of Circuits and Systems**

**Virtual Conference: June 29-July 26** [v.semi.org.cn/cstic](https://v.semi.org.cn/cstic)

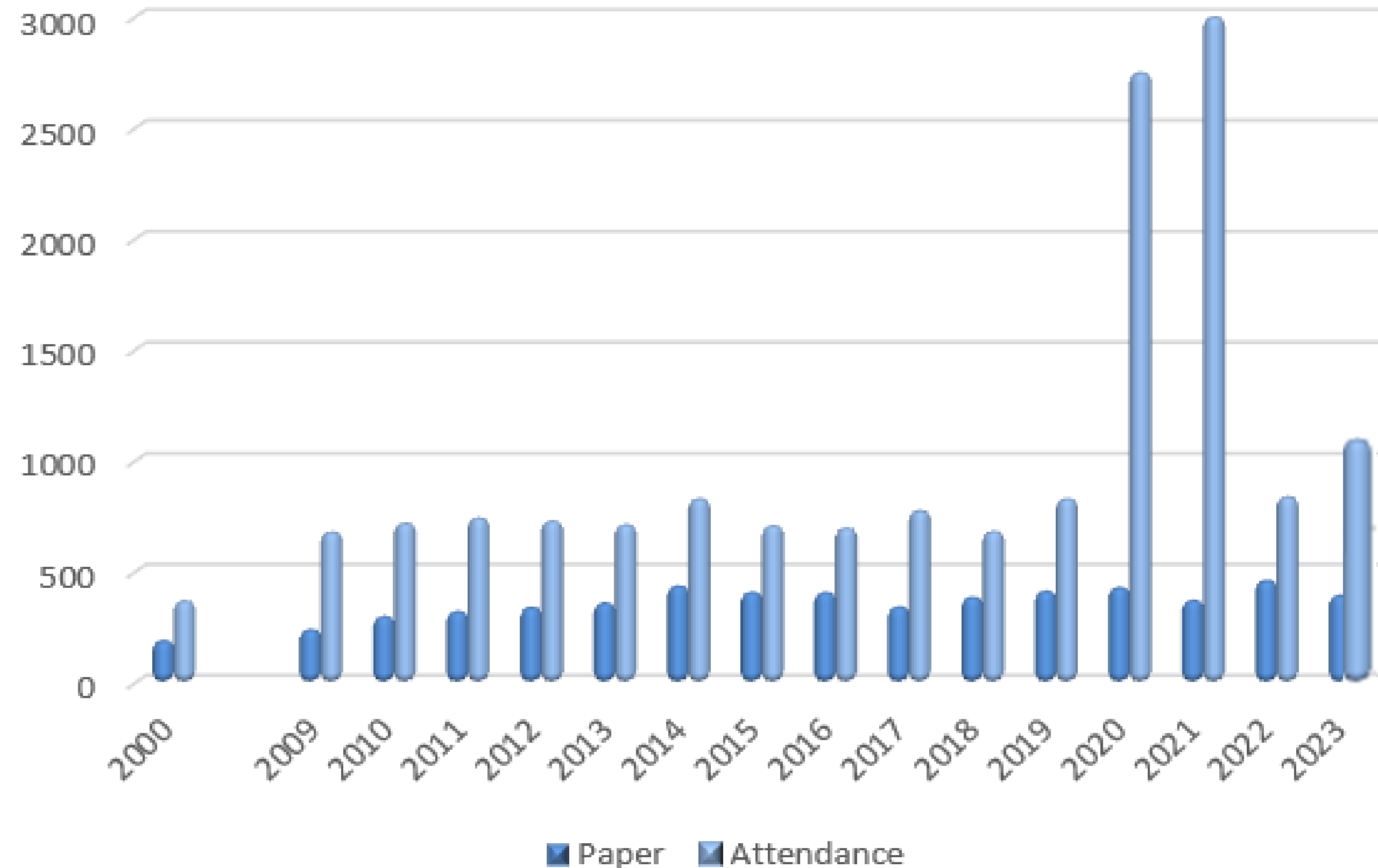
	Zhongrui Wang University of Hong Kong		Mario Lanza King Abdullah University of Science and Technology (KAUST)
	Yasin Ekin Paul Scherrer Institute		Toru Fujimori FUJIFILM Corporation
	Henri van Helleputte ASML Netherlands B.V.		Allen Chang JSR Corporation
	Yunlong Li Zhejiang University	 中国半导体技术大会	
	Yan Sun Beijing NAURA Microelectronics Equipment Co., Ltd		Bing Liu Anji Microelectronics Technology (Shanghai) Co., Ltd
	Hongqi Xiang InvenTech Materials		Huawei Li Institute of Computing Technology, Chinese Academy of Sciences
	Alan Wang Baylor University		Zhen Zhang Uppsala University





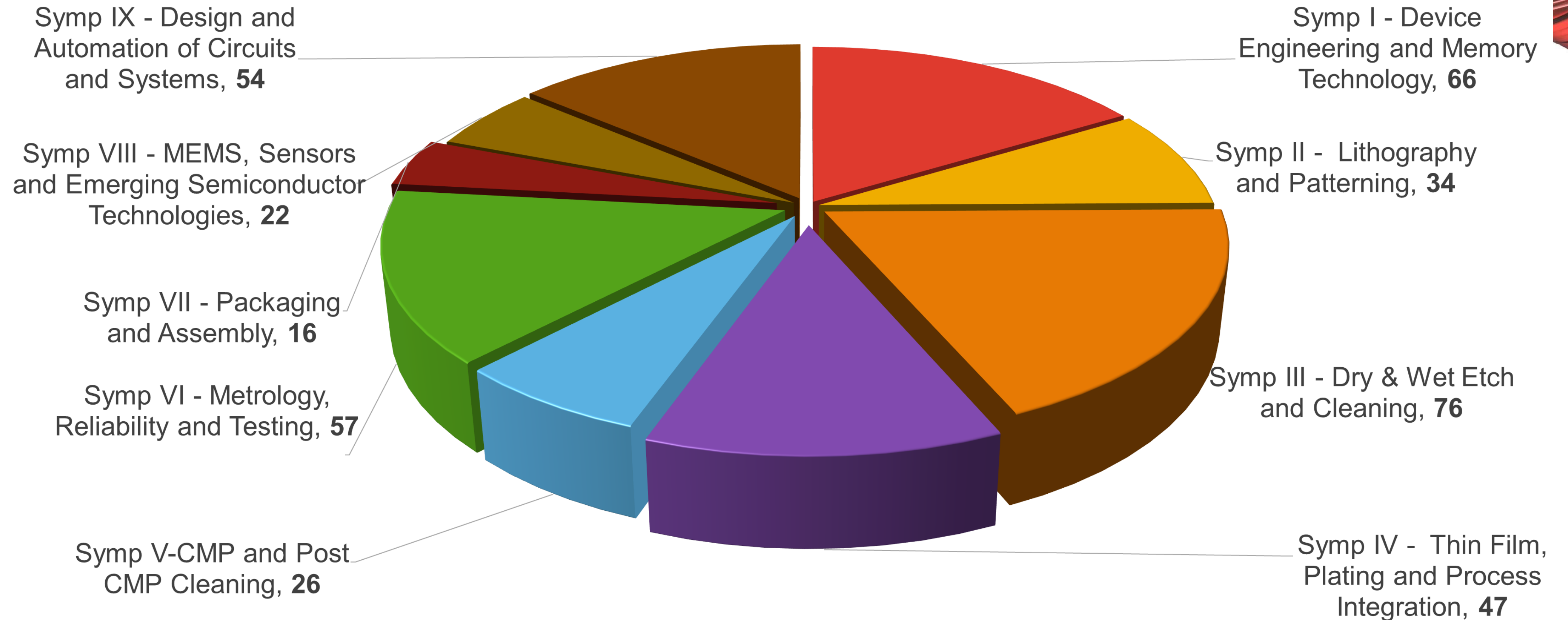
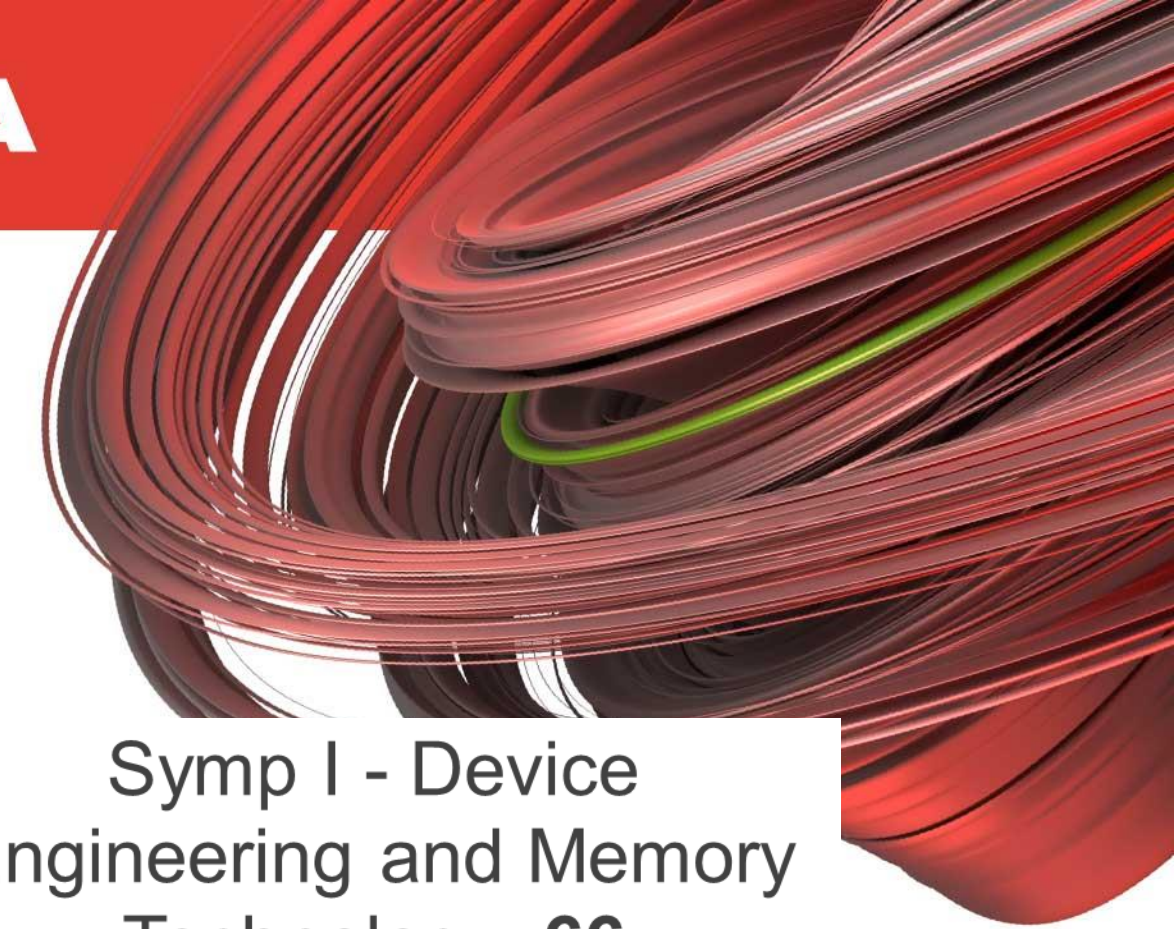
# CSTIC 2023

- Largest and most comprehensive, influential annual industrial semiconductor technology conference in China and Asia
- **403 abstract submissions** have been collected. **724 registered attendees joined the onsite conference**, while **online registration is 1061**, including overseas attendees from US, Israel, Japan, Korea, Germany, Sweden, Switzerland, Singapore, UK, Russia, Canada, France, Saudi Arabia, Taiwan China, HK China and etc.





# CSTIC Symposium Abstract Submission

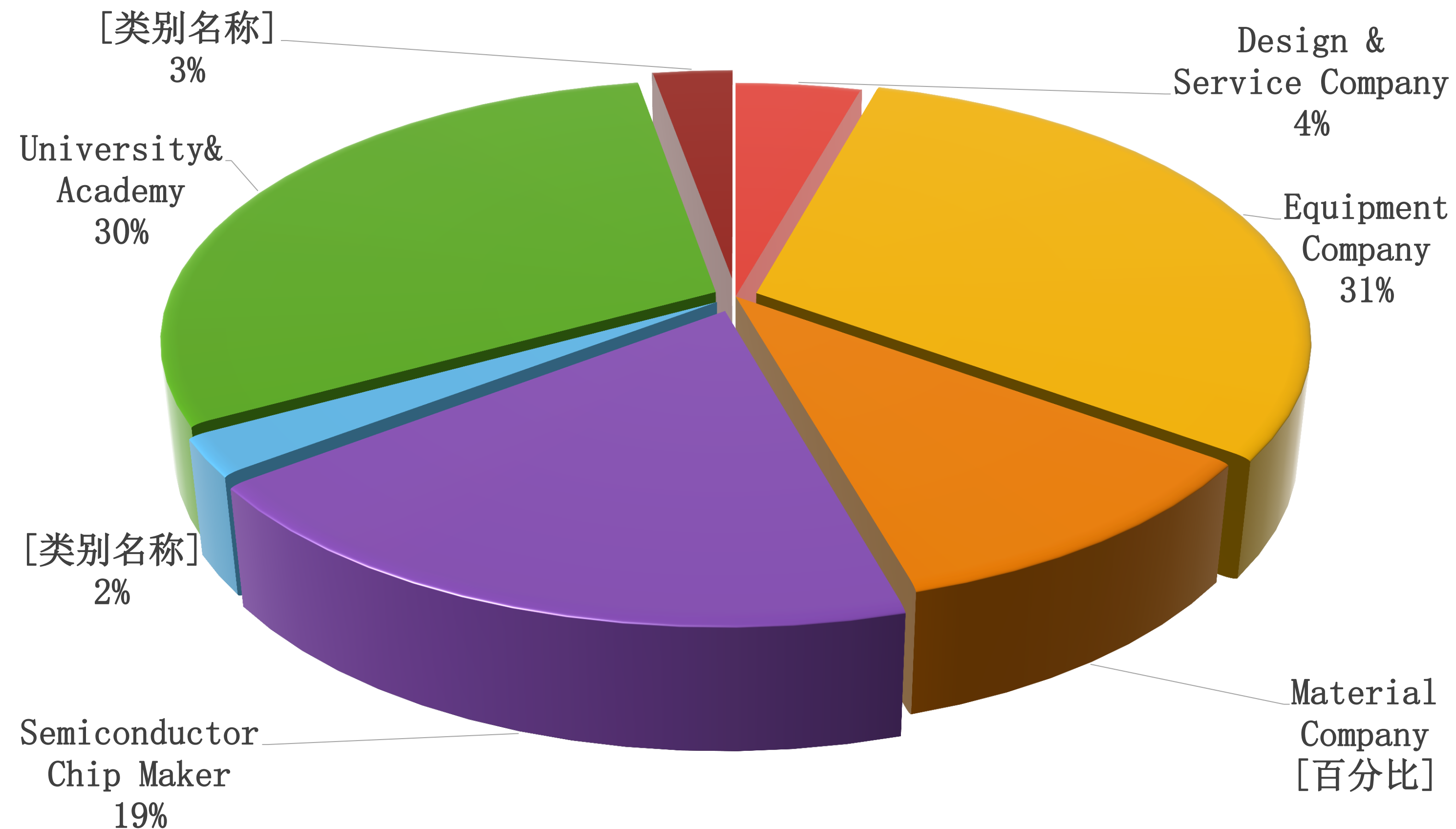


*\*Totally 205 manuscripts published at IEEE*



# Industry and Academy Cooperation

## 67% Attendees from Industry



- 67% attendees from industry
- 30% attendees from academy
- Attendees were from around 190 different companies or institutes
- Chip companies like SMIC, HLMC, HHGrace, JCET, CXMT, CXMC, NXP, Wuhan Xinxin, Intel, AMD and etc. joined the conference



# 190 Participating Companies

5N Plus China  
AAA  
ACM  
ADVANTEST  
Air Liquide  
Air Products  
AMD  
AMEC  
Ancu Technology  
Anji  
Applied Materials  
ASM  
ASML  
Axcelis  
BDA  
Beihang University  
Beihang University Hefei Research Institute  
Beijing Integrated Circuit Equipment Innovation  
Cente  
Beijing Jiaotong University  
Beijing Naura  
Beijing NeuCloud  
Beijing Sunrise Technology  
Beijing Superstring Memory Research Institute  
Beijing University of Chemical Technology  
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# 190 Participating Companies

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Shinko Control Technology  
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# WFD Training Courses

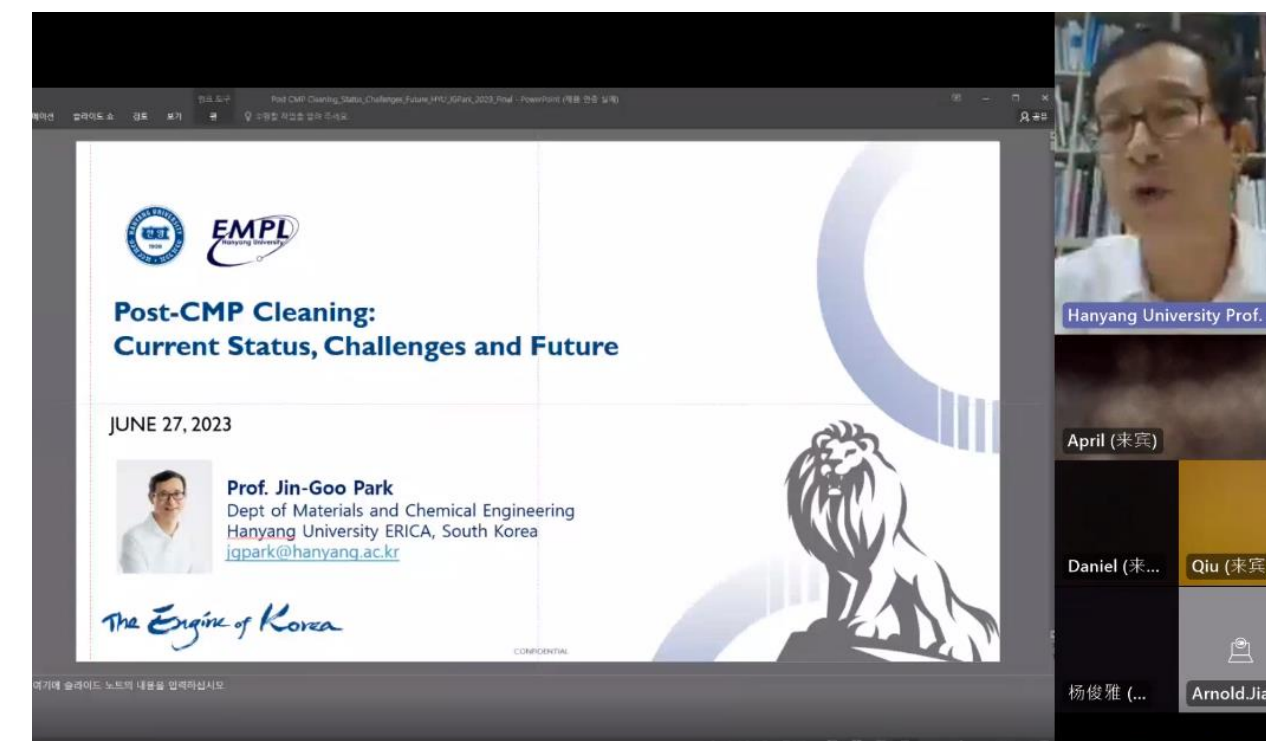
Lithography process and key technical aspects in exposure tools, materials, and the future development roadmap

Dr. Qiang Wu, Professor of the School of Microelectronics of Fudan University



## Post CMP Cleaning

Dr. Jin-Goo Park, Professor of Hanyang University, Korea





# Attendees to Plenary Session and 9 Symposia

CSTIC 2023 Attendee Number	724
Plenary Session	605
Symp I - Device Engineering and Memory Technology	250
Symp II-III Joint Session	199
Symp II - Lithography and Patterning	235
Symp III - Dry & Wet Etch and Cleaning	314
Symp IV - Thin Film, Plating and Process Integration	389
Symp V - CMP and Post-Polish Cleaning	157
Symp VI - Metrology, Reliability and Testing	143
Symp VII - Packaging and Assembly	77
Symp VIII - MEMS, Sensors and Emerging Semiconductor Technologies	52
Symp IX - Design and Automation of Circuits and Systems	129



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**Dr. Hanming Wu**  
Conference Chair



**Dr. Beichao Zhang**  
Conference Executive  
Co-Chair



**Prof. Ru Huang**  
Conference Co-Chair



**Prof. Cor Claeys**  
Conference Co-Chair



**Dr. Steve X. Liang**  
Conference Co-Chair



**Dr. Qinghuang Lin**  
Conference Co-Chair



# Symposium Chairs



**Dr. Ru Huang**  
Symp-I Chair,  
Conference Co-Chair  
Professor of Peking  
University,  
President of Southeast  
University,  
Academician of Chinese  
Academy of Sciences



**Dr. Linyong (Leo) Pang**  
Symp-II Chair  
Vice President, D2S Inc.,  
USA



**Dr. Ying Zhang**  
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Consultant



**Dr. Xiaoping Shi**  
Symp-IV Chair  
CTO, Beijing Naura  
Microelectronics, China



**Dr. Xinping Qu**  
Symp-V Chair  
Professor, Fudan  
University, China



**Dr. Xiaowei Li**  
Symp-VI Chair, Deputy  
Director, ICT, CAS, China



**Dr. Steve X. Liang**  
Symp-VII Chair



**Dr. Qinghuang Lin**  
Symp-VIII Chair Director,  
Lam Research, USA



**Prof. Weikang Qian**  
Symp-IX Chair  
Assistant Professor ,  
University of Michigan-  
Shanghai Jiao Tong  
University Joint Institute,  
China



**Dr. Hsiang-Lan Lung**  
Poster Chair  
Director, MXIC, Taiwan,  
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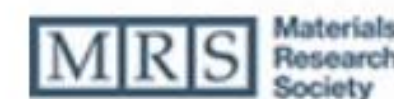
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# CSTIC 2024

Time: March 17 ~ 18, 2024

CSTIC 2024 call for papers and manuscript deadlines:

Abstract Due: Sep. 30, 2023

Author Notification: Oct. 15, 2023

Manuscript Due: Dec. 26, 2023

Copyright Due: Feb. 20, 2024

Presentation Due: Feb. 20, 2024

Conference Date: Mar. 17-18, 2024





Thank you